



ATLAS

Abritta Costa Igor, Albicocco Pietro, Antonelli Mario, Arcangeletti Chiara, Battisti Marco, Beretta Matteo Mario, Buadze Beka, Capitolo Emilio, Chubinidze Zaza, Croce Antonio, Dané Emiliano, Gardini Alessia, Gargana Riccardo, Gongadze Levan, Ligi Carlo, Liedl Andrea, Mancini Giada, Pileggi Giuseppe, Ponzio Bruno, Pudzha Dennis, Rosatelli Filippo, Testa Marianna, Tinti Gemma, Vilucchi Elisabetta, Gianmario Cesarini

Si ringraziano i tecnici del servizio vuoto e della metrologia della DA, e tutti i tecnici e progettisti della DT

NSW Operation in ATLAS

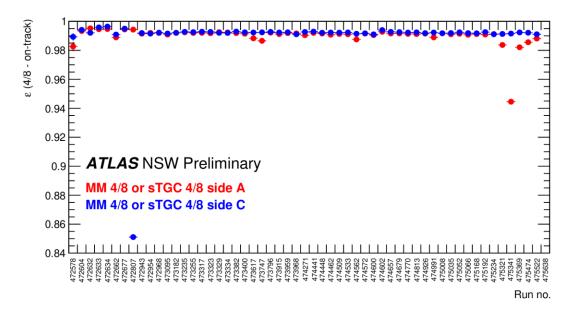
LNF still involved in operation and maintenance activity. Several responsibilities covered during the construction and installation phases

Micromegas HV status

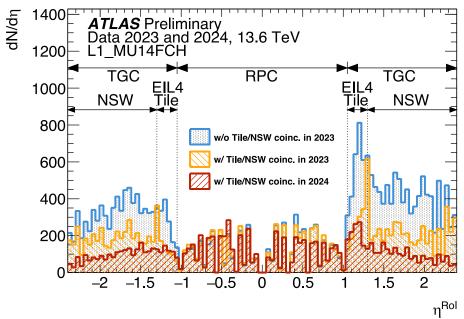
Gas mixture with Isobutane → Only 1-2% channels are not working

Data Taking & Performance

- DAQ stability very much improved: stable efficiency >95%
- Track reconstruction is >99%



NSW in Level-1 Trigger chain included: all sTGC Pad and MM sectors in since May 28th 2024
Fakes rate rejection ~11 kHz and Tigger efficiency up to 98%





First Run2+Run3 combined result!

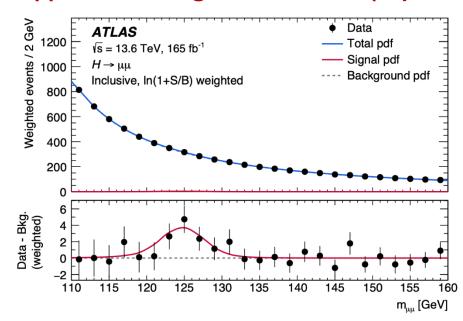
LNF activity on H→ZZ*→4l

decay channel

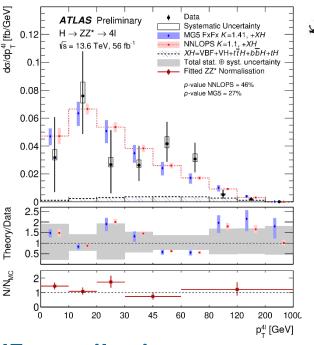
H

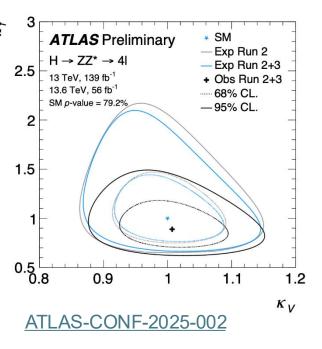
reporting the property of the pro

H→μμ observed significance: 3.4σ (exp. 2.5σ)



2507.03595 (submitted to PRL)





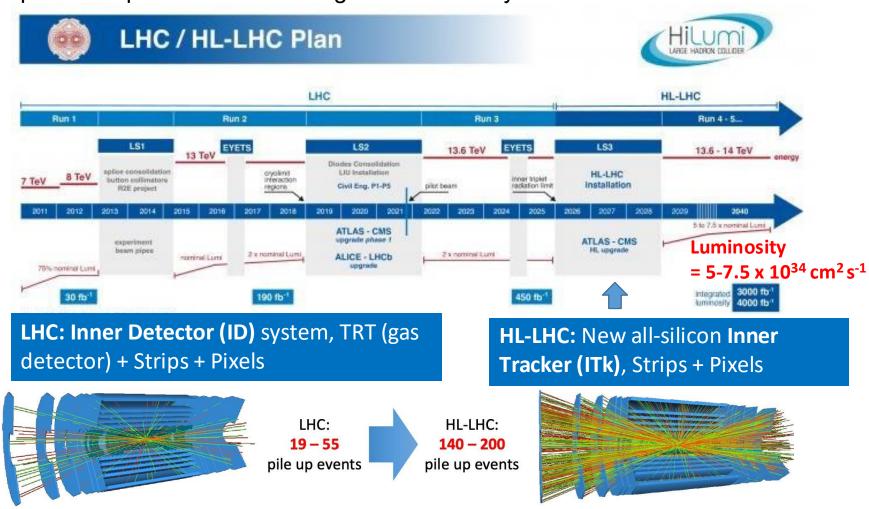
LNF contribution

C. Arcangeletti, G. Mancini

- HZZ group convenership
 - Focusing on performing measurements of the Higgs boson properties in the H→ZZ* decay channel at 13.6 TeV
 - Differential and STXS measurements and BSM interpretation
 - First ATLAS evidence of the H→µµ decay channel!
 - Study of Quantum Entanglement in the Higgs decay in two vector bosons

HL-LHC

The LHC will be upgraded to the High Luminosity-LHC (HL-LHC) to produce up to 4000 fb⁻¹ of integrated luminosity until 2040



Requirements for pixel detector at HL-LHC

Instantaneous conditions: pile-up, luminosity

- High trigger rate: 1 MHz
- High granularity: occupancy at 1 %

Integrated effects

Integrated luminosity x10
 → Radiation hard technologies
 up to 2·10¹6 neq/cm²

A replacement of the current ID detector is by far not enough!



ITk: The New Inner Tracker

All-silicon tracker

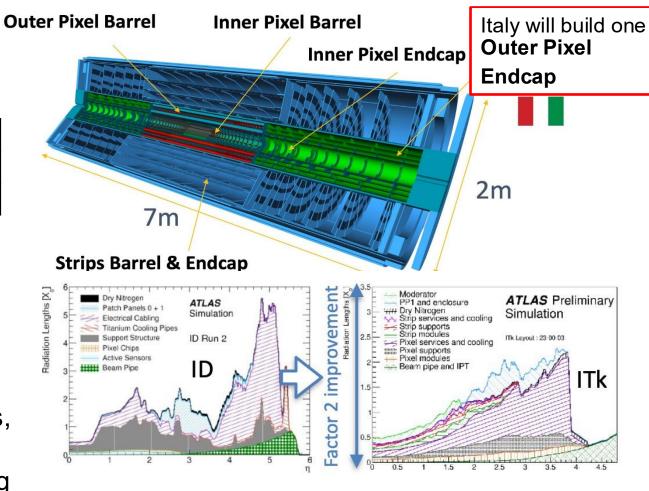
ITk (ID)	Area (m²)	# Modules	# Channels (M)
Pixels	13 (1.6)	9164 (2000)	5100 (92)
Strips	165 (61)	17888 (4088)	60 (6.3)

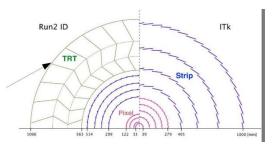
Improved tracking

- Coverage up to |η|<4 (ITk) from |η|<2.5 (ID)
- Finer segmentation:
 - 50x50μm² or 25x100μm²
 - ID: $50 \times 400 \ \mu m^2 \ \text{or} \ 50 \times 250 \ \mu m^2$
- Reduced material: Carbon Fibre structures,
 CO₂ cooling with thin Ti tubes walls,
 advanced serial powering, data link sharing

Radiation hardness:

- n-in-p pixel sensors (n-in-n for ID)
- Thinner sensor 100-150 μm (200-250 μm in ID)







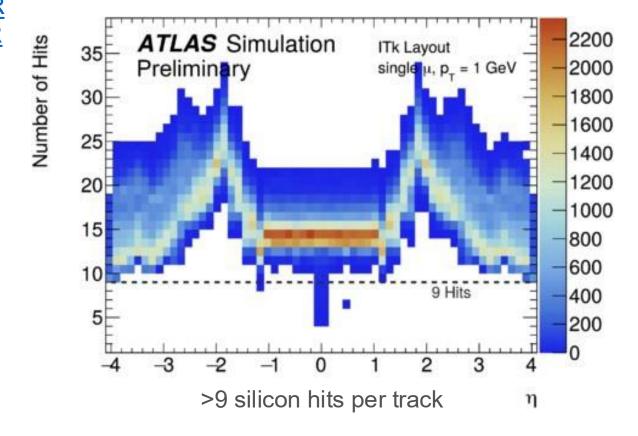
ITk Performances

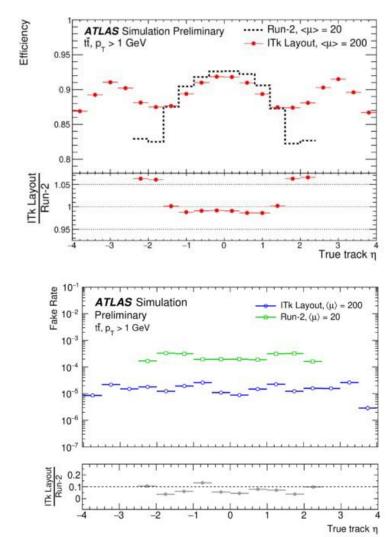
Important LNF contribution to design and simulation, for $|\eta|$ <4 coverage and pixel size decision

ATL-PHYS-PUB-2019-014

ITk Pixel TDR
ITk Strip TDR

M.Testa



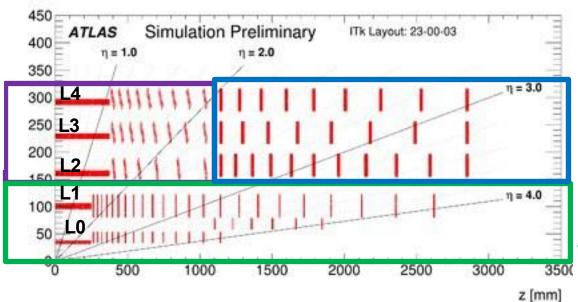


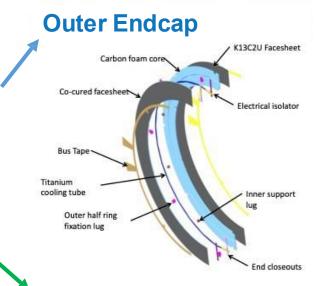


ITk Pixel Detector

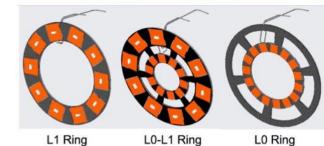
Local supports: Different designs to support flat and inclined module mounting







Inner System



IS to be replaced after 2000fb⁻¹ to reduce radiation damage.

L0 placed 34 mm from beam pipe.

Modules: two main module types, quad & triplet.

Triplet	
Quad	40

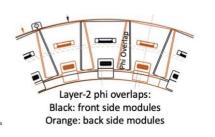
40

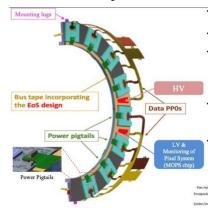
Layer	Module type	Sensor type	Sensor thickness [um]	Pixel size [um²]
L0 barrel	Triplet	3D n-in-p	150	25x100
L0 rings	Triplet	3D n-in-p	150	50x50
L1	Quad	Planar n-in-p	100	50x50
L2-4	Quad	Planar n-in-p	150	50x50



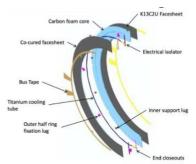
ITk Pixel Outer Endcap

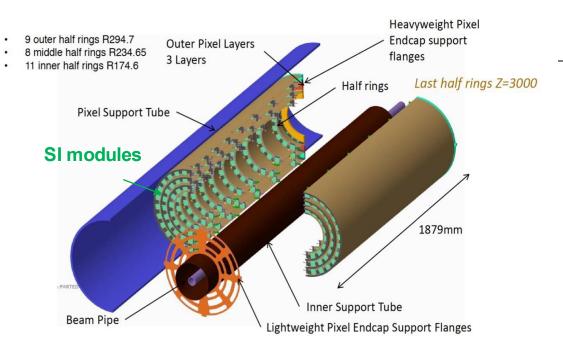
- Three layers of half-rings (HR) loaded into carbon fibre halfcylinders
- HR are strategically placed in z to provide hermeticity in η
- Modules on both sides of HR ⊥ to beampipe → Φ hermeticity
 - >= 5 pixels overlap in φ.
- Each HR side holds one serial-powering chain:
 - 16/22/26 Modules for Layer2/3/4



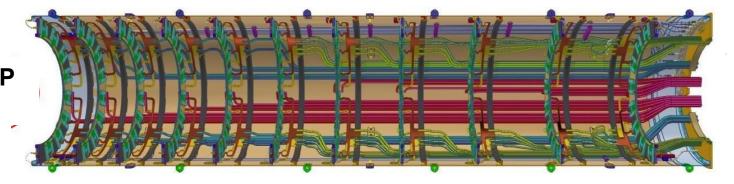


Half-rings are C-foam /
C-fibre "sandwiches"
with embedded cooling
pipe and fixation lugs





Cooling lines, data and electrical cables, run between outer rims of rings and inner surface of cylinder





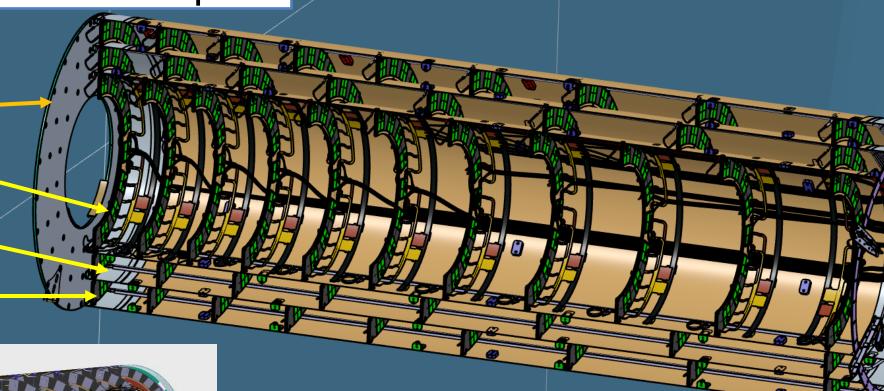
ITk Pixel Outer Endcap

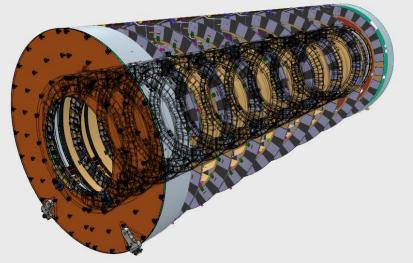
IP FLANGE (Low-z)

L2 HR: 11 per HS

L3 HR: 8 per HS

L4 HR: 9 per HS





Dimensions:

L4 diam: 750,2 mm L3 diam: 528.1 mm

L2 diam: 408 mm

Length: 1888 mm

SERVICE FLANGE (High-z)

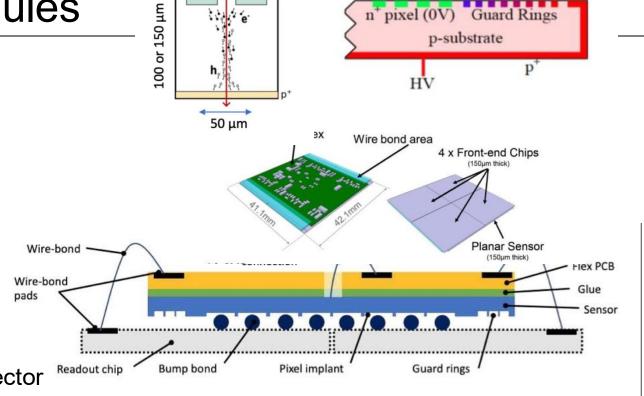


Sensor, Front-End Chip and Modules

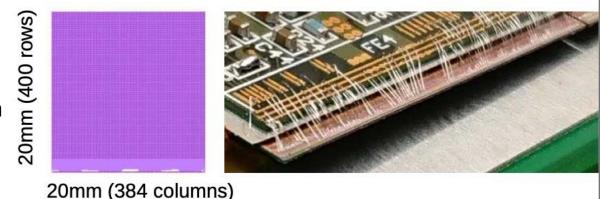
- Planar Sensor n-in-p
- Front-End Chip by RD53 collaboration
 - Read out trigger frequency at 1 MHz
 - 4 data lines at 1.28 Gbps
 - Uplink sharing
 - Rad-hard up to 500 MRad
 - 65nm technology
 - Chip size: 400 x 384,
 50x50 µm² pixels, 2.0 x 2.1 cm²
 - Shunt-LDO regulator for serial powering
 - 8912 data links / endcap from modules to off-detector electronics

Modules: 4 FE chips bump-bonded to sensor

- Cu-Kapton flex hybrid glued to sensor for connection to power, slow controls and data distribution
 - Wire bonds connect the flex to the FE chip(s)
 - "pigtails" connecting modules to power / data
- 1172 modules/endcap

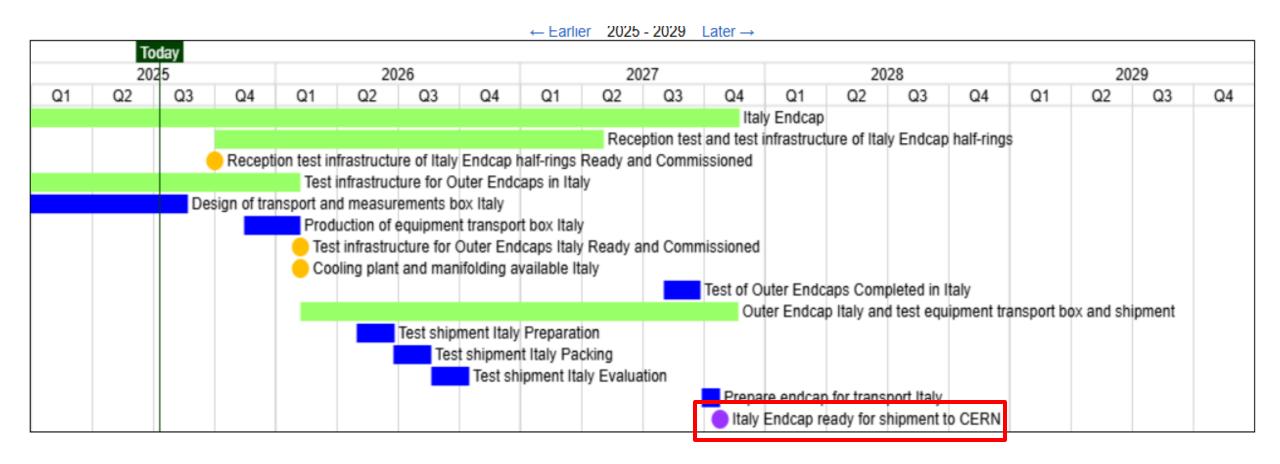


Planars

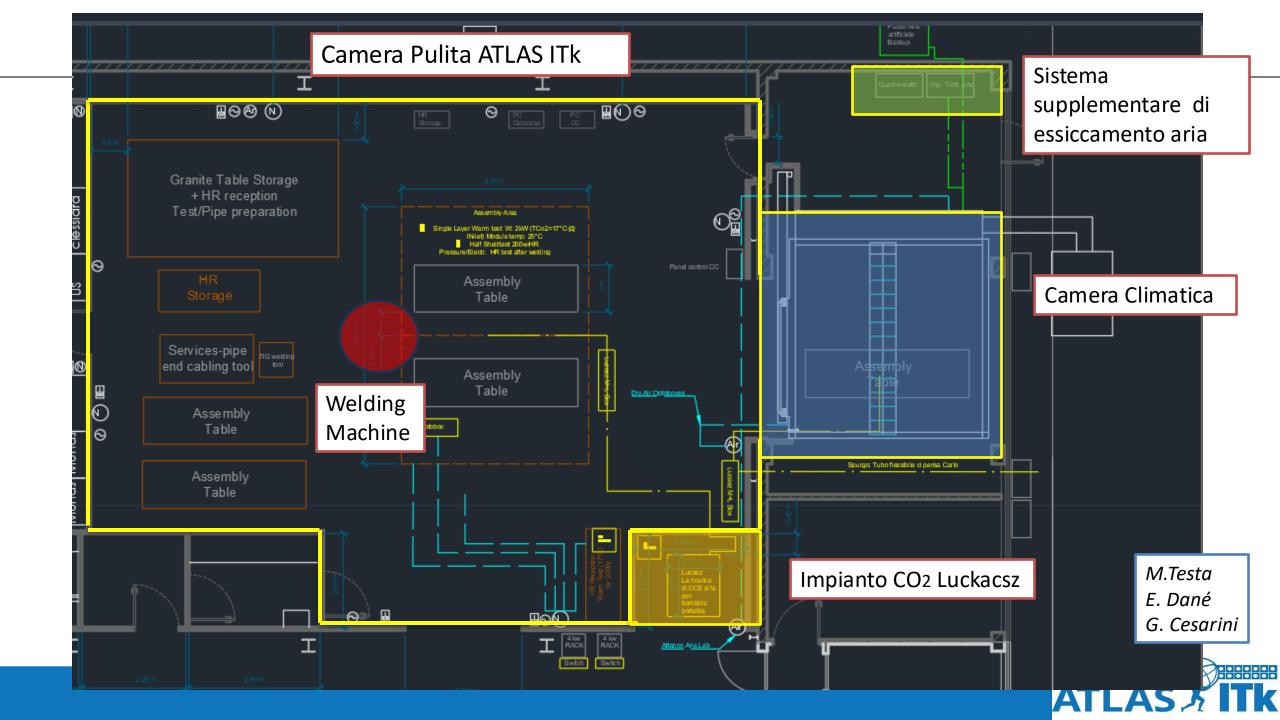




Schedule from the last statusing





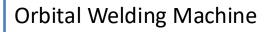


CO₂ cooling LUCASZ Light Use Cooling Appliance for Surfaces Zone



- Constructed and commissioned in 2021 at DESY
- Successful test with merging lines at LNF
- → 20 g/s CO₂ flow
- Successful Integration with interlock system



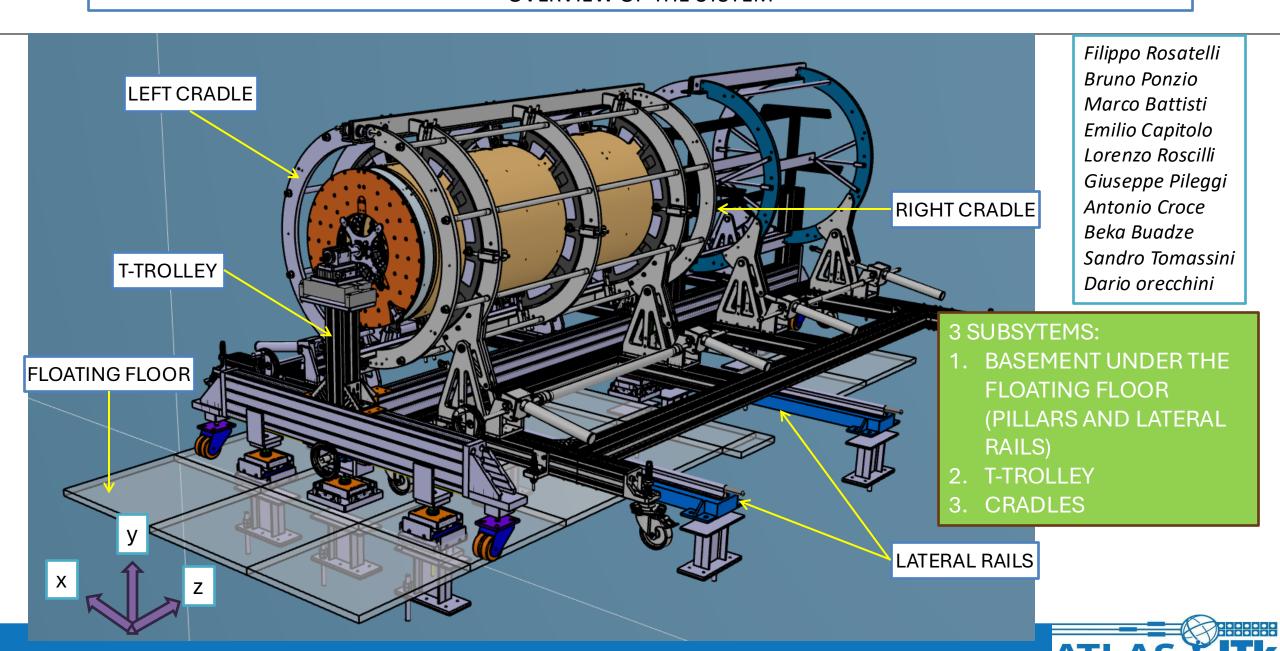








OVERVIEW OF THE SYSTEM



Material from Naples shipped to LNF, ready to be mounted

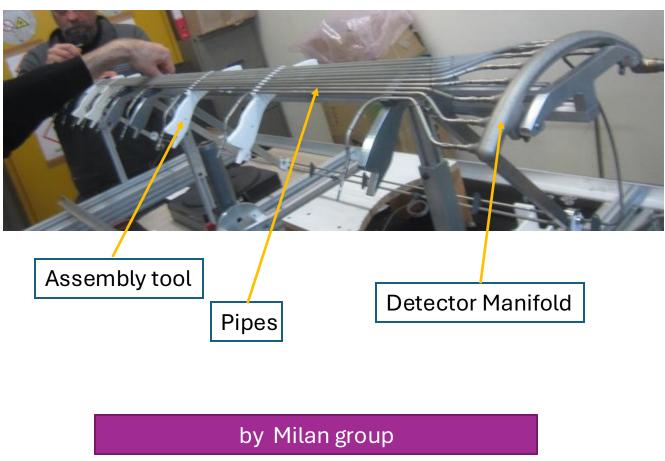


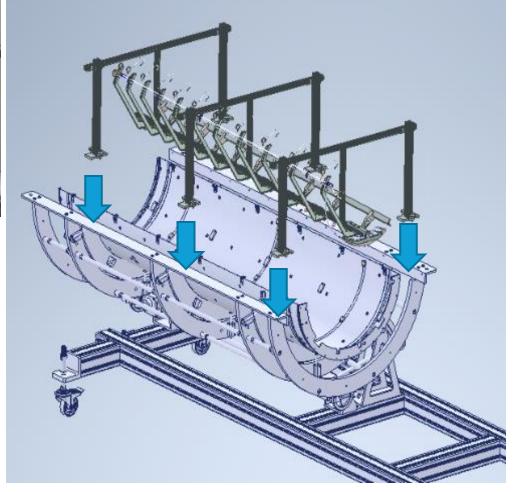


Missing the part of the service, the material is just arrived and some other parts are produced in LNF so we can start to add this part. The idea is to mount already closed the upper part of the cradle and then connect it to the bottom part. Missing the part of the connection between the cradles and carriages. Arriving these parts soon to perform some test.



PIPE INSERTION TOOL

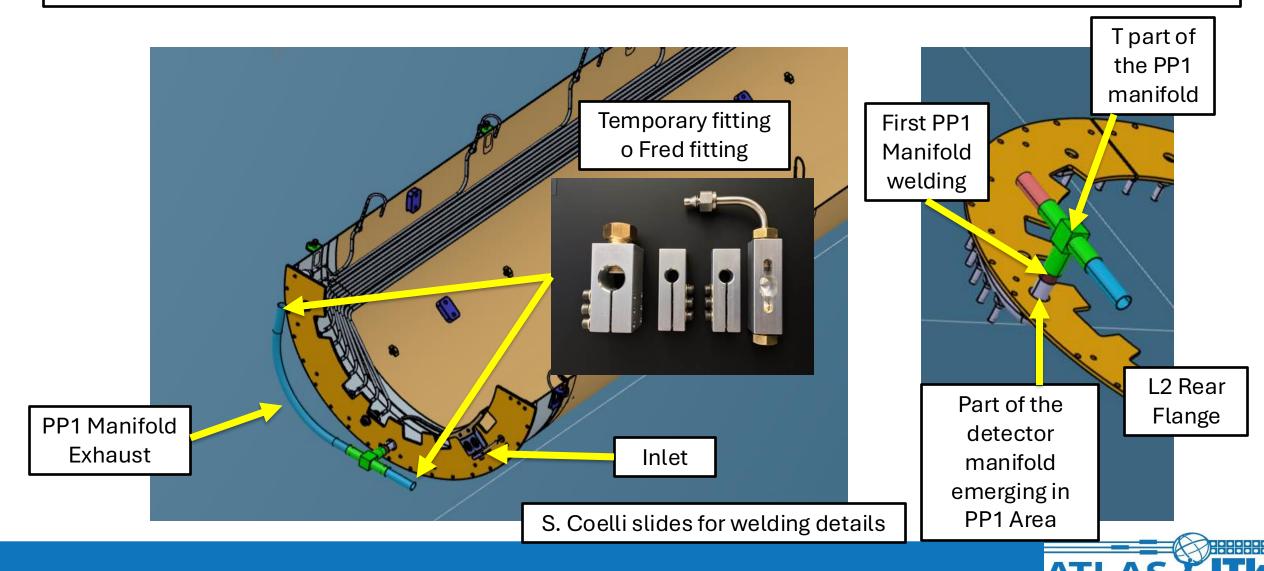






FIRST PP1 MANIFOLD WELDING

Once the pipes are in position the first welding for connecting the exhaust and inlet PP1 manifolds is performed



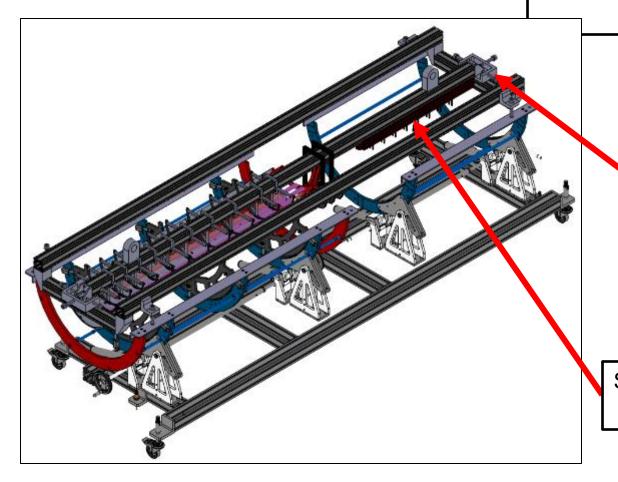
CABLE HARNESS INSERTION TOOL

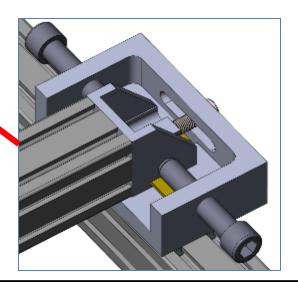
by UK group

The position of the cable harness is adjustable on the cradle.

The plate at either end can slide on a low-friction interface

Horizontal position is adjusted by screws



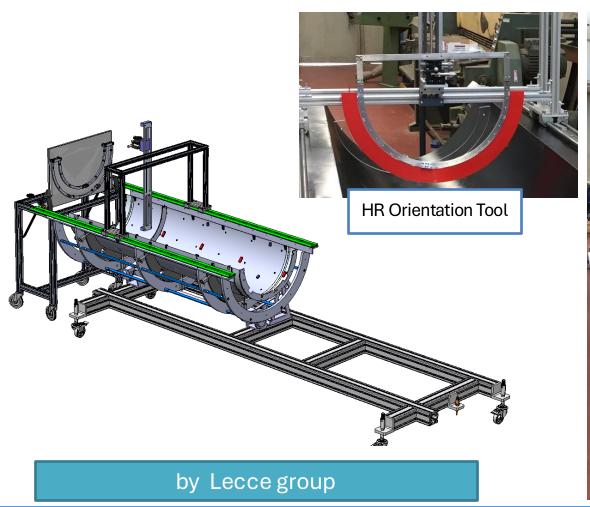


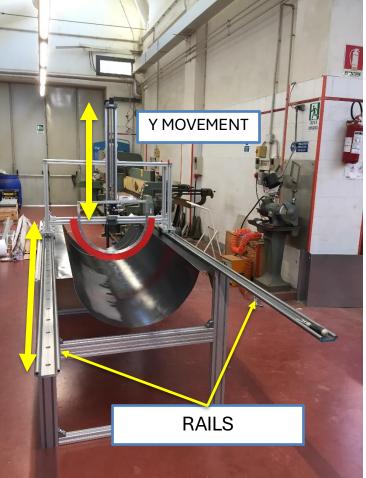
Support of cables in order to transfer to the integration tooling



HALF RINGS INSERTION TOOL

Horizontal rails are positioned on the rotating cradle for movement along z axis. A vertical rail is devoted to move down the HR.



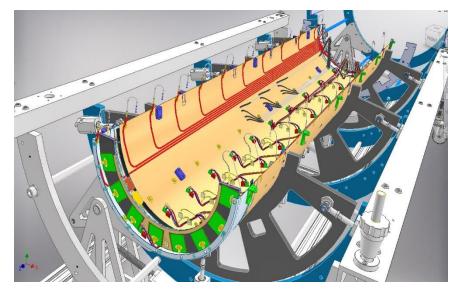


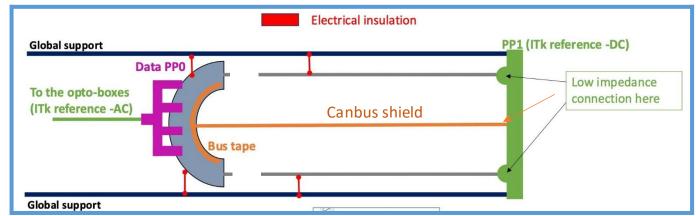




Half-ring test after insertion

- QC: measure the isolation resistance between the GND pad of bus-tape and the HS
- Connect HR to pwr and data type-1 cables
- Bus tape is grounded

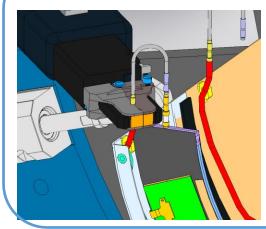




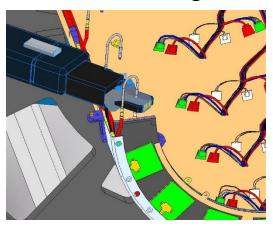


Three weldings per HR

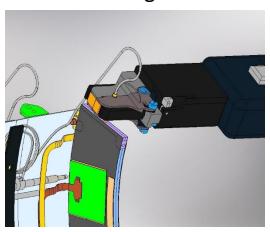
1° exhaust welding



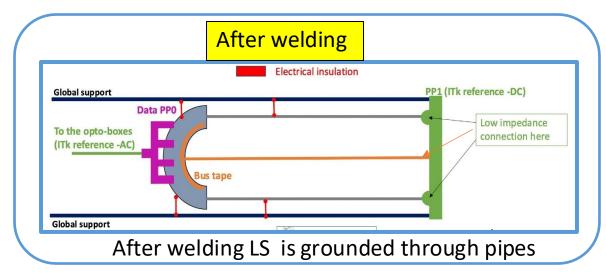
2° exhaust welding



1° inlet welding



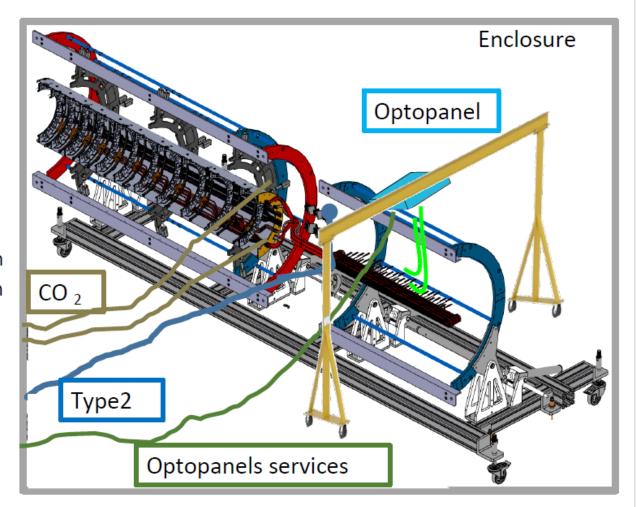
- Leak test, Pressure test 162 bar, Leak test
- Temporary ground the pipes nearby HR to protect modules
- Re-test connectivity one HR at the time after welding to check no damage to module or services





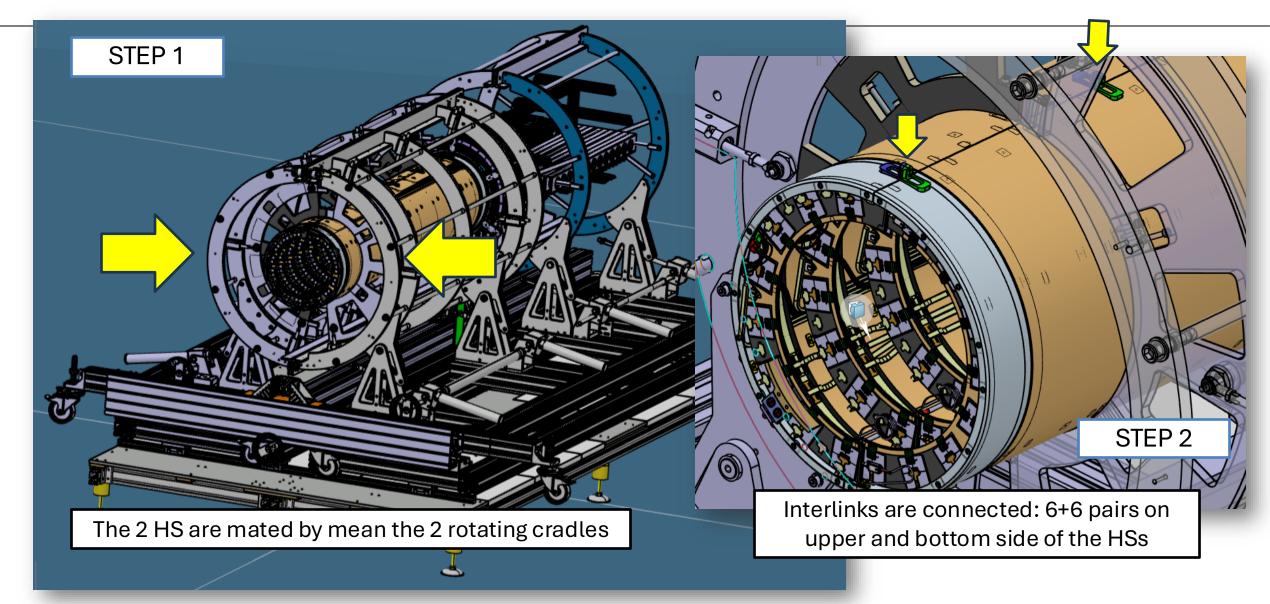
OEC Half-cylinder integration & test

- Move HS into climate chamber which serve also as test box
- Function cold test
 - Dew Point < -60 C
 - T_{ev CO2} ~ -15 C
 - Normal powering mode
 - Digital, Analog, Threshold scan
 Disconnected bump-bond scan
- Thermal cycle [+40 45C]
 - Detector Off
 - All service can be kept inside (TBC)
- Repeat cold test



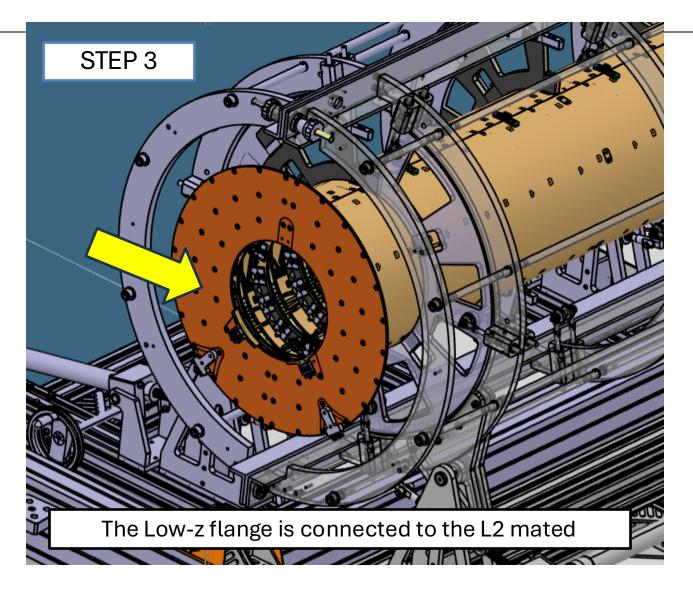


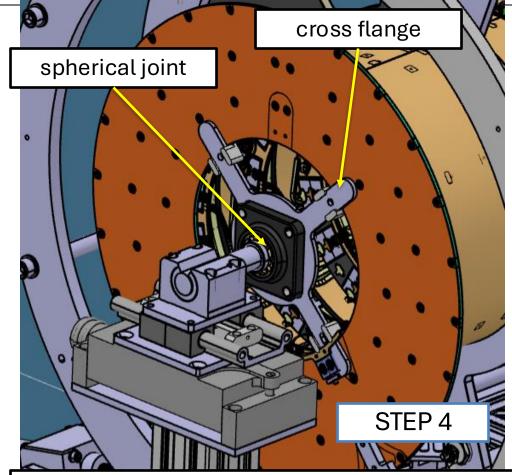
HALVES SHELLS MATING: ASSEMBLY PROCEDURE





HALVES SHELLS MATING: ASSEMBLY PROCEDURE

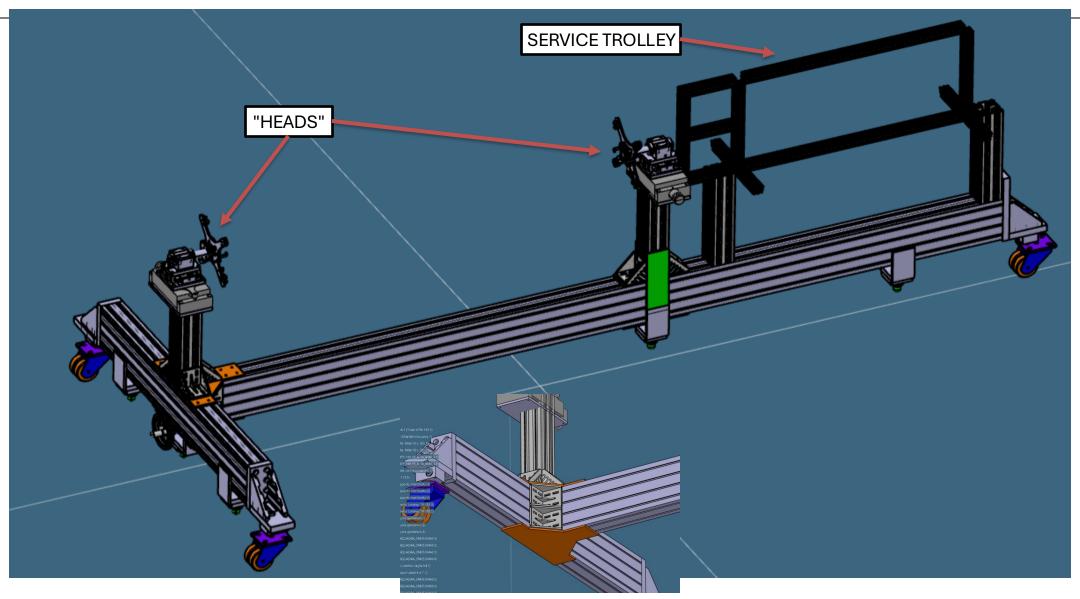




Exploiting the spherical joint and the linear stages the cross-flange is oriented and adapted to the low-z flange position



STATUS OF T-TROLLEY

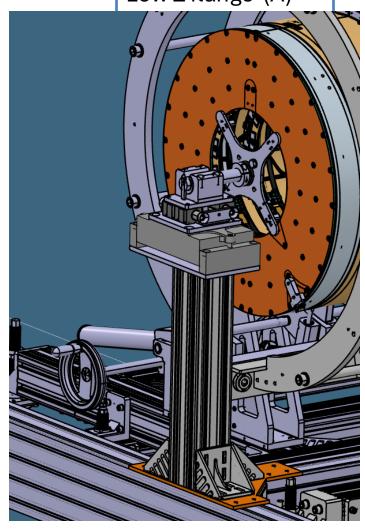




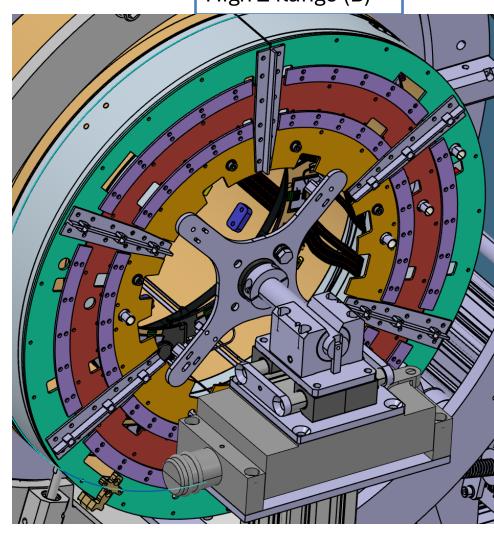
Integration Heads

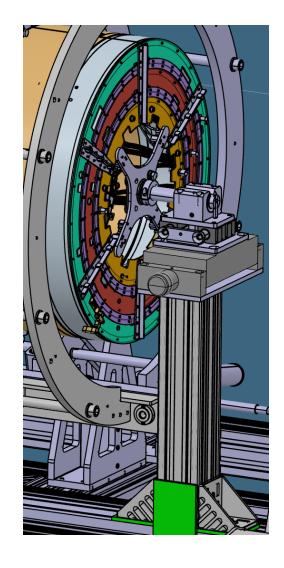


Low Z flange (A)



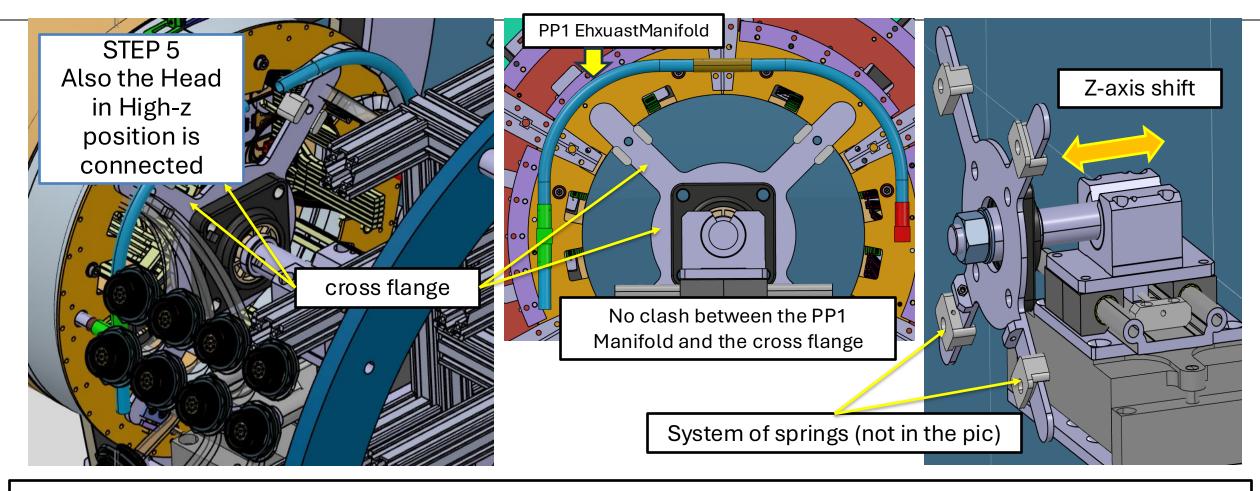
High Z flange (B)







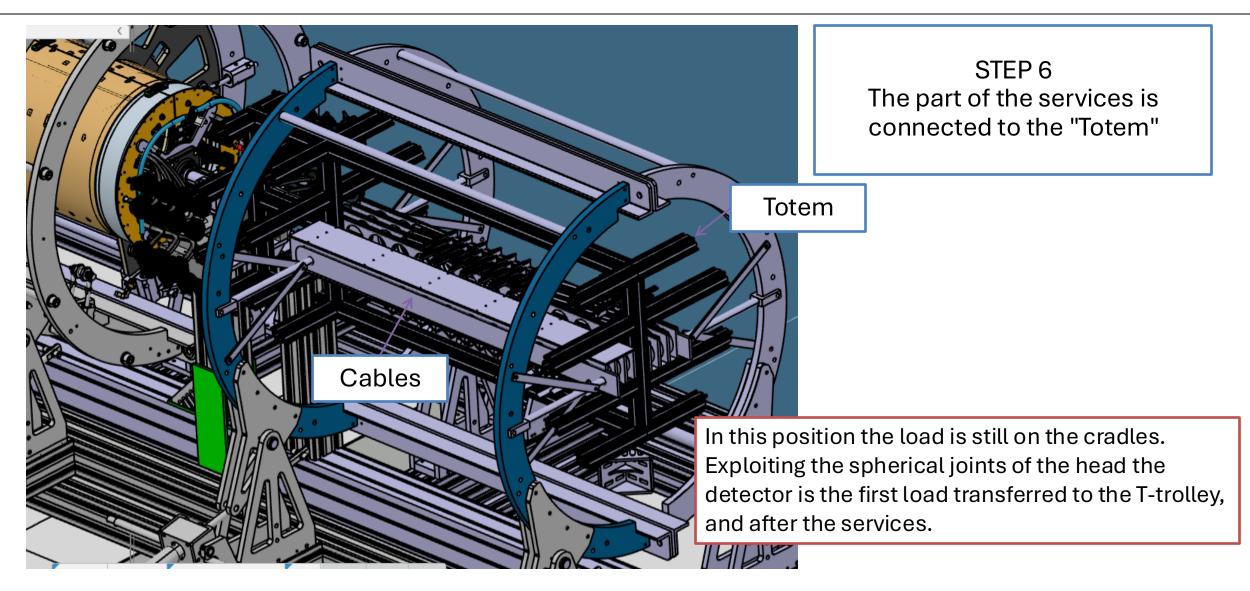
HALVES SHELLS MATING: ASSEMBLY PROCEDURE



As can be seen in the figure there is no clash between the PP1 manifold and the detector support. By taking advantage of the 2 springs present in the lower arms of the cross-flange and the movement along the z axis allowed by the bearing, the detector support can be connected to the rear flange.



HALVES SHELLS MATING: ASSEMBLY PROCEDURE





Test on complete Layer

Low impedance connection of the two HS

Ground layer to floor

Connectivity Test for complete layer

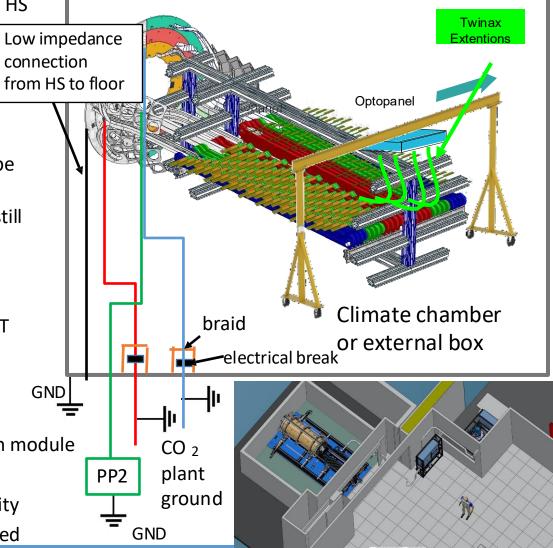
Use Lowe Power mode

Cooling through climate chamber

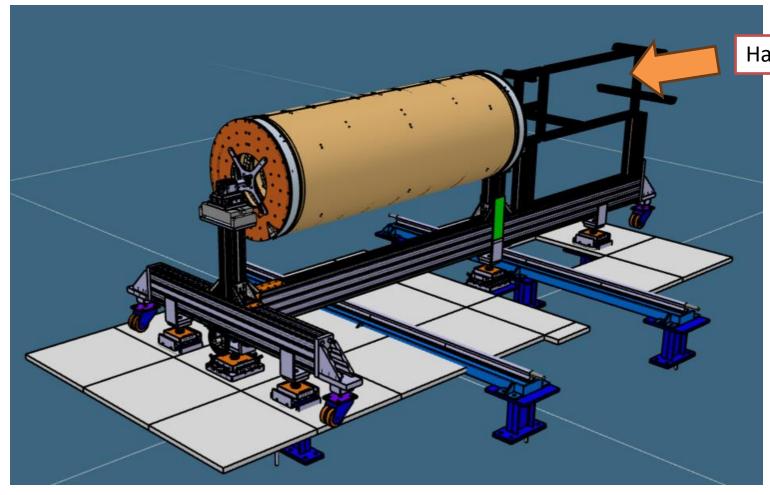
 Demonstrated with prototype with T_{air} ~ - 35 C (in bkp)

Helping with CO₂ cooling is still possible

- LV lines:
 - chip register reading
 - MOPS reading of module V and T
 - Tlock
- Data transmission:
 - Uplink: digital scan and BERT
 - Downlink: Configure a FE in each module
- HV lines:
 - PS will have not enough sensitivity
 - Open point: strategy to be defined



Connectivity Test on full endcap pre-shipping



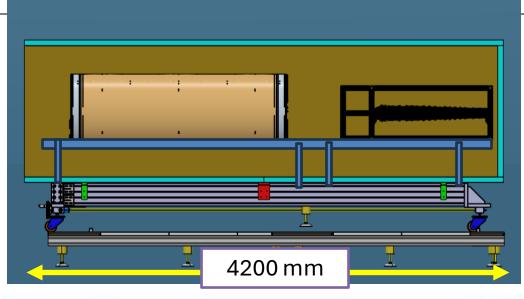
Harness not present in picture

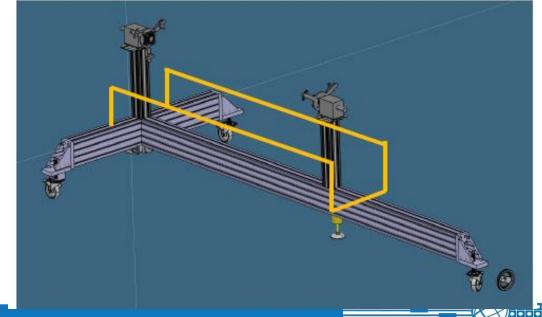
By mean the lifting system under the floating floor, the T-trolley is positioned on wheels and then can be moved into the Climatic Chamber for the final test.

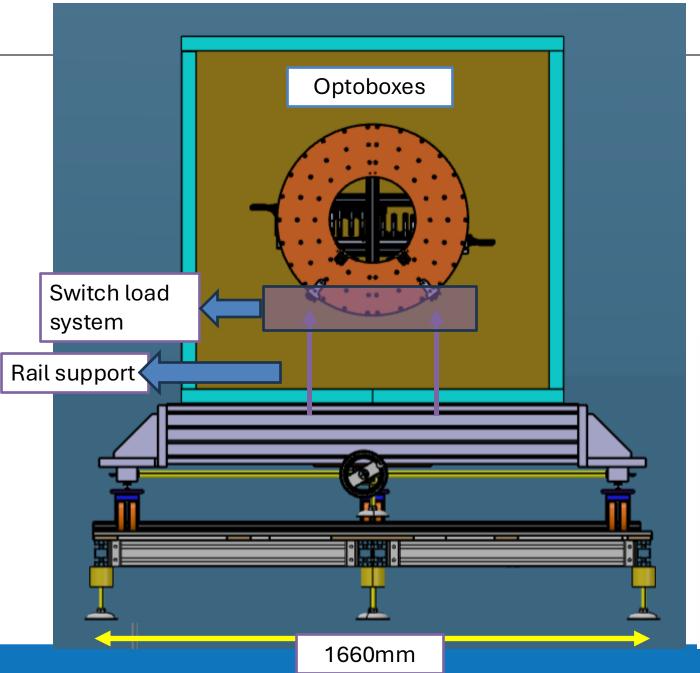
- Final test in the climate chamber
 - Low power mode
 - Cooling demonstrated with prototype with Tair ~ - 35 °C
 - Helping with CO2 cooling is still possible



Solution with a smaller box







Prototypes

The idea is to have the whole detector in a prototype/mockup version in in order to test the mating (empty), then the insertion of the piping, the insertion of the cables and the Half Rings, and then the mating with the populated HS and the PP1 manifold (see tomorrow talk) for each layers. Some HRs could have the piping to perform some welding test.

What we have so far:

Half Shell: we have one Half L4 (from Liverpool) and 2 L2 (from Aviacompositi).

- Lugs: all printed in ULTEM (by Naples)

- In production the tool for the positioning the lugs of the HS (by Giuseppe Pileggi LNF)

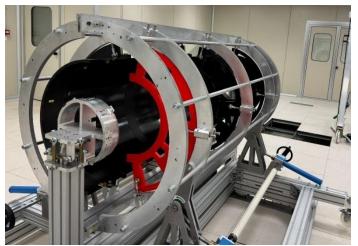
Half rings: 2 HRs per type (6 in total) made in LNF (E. Paoletti, R. Tesauro)

Lz flange: already printed (ABS)

Hz flange: Printed for L2 (ABS)

"Spider" Flange: Produced (F. Rosatelli)









QA Tests are foreseen to check the functionalities of the system:

- Thermal Cycling on the HS connected to the rotating cradle
- Thermal Cycling and functional test on the HS equipped with HRs





Circle Relationship A::Cerchio1 sx Criteria Measured Diameter 839.95 Circularity 0.26 X 4.49 Y 1060.79 Z 437.96 RMS 0.09 Measurements 13

Circle Relationship A::Cerchio2 sx Criteria Meas

Diameter

Circularity

Measurements

RMS

Circle Relationship A::Cerchio3 sx

Diameter Circularity

RMS

Measurements

Criteria Measured

Measured 839.93

0.21

3.37 1059.88 1107.99

0.06

839.33

2.55 1059.88 1778.25

0.05

		-	
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123			
	A. 2 3.		

Circle Relationship		
A::Cerchio1 dx		
Criteria	Measured	
Diameter	839.20	
Circularity	0.21	
X	3.52	
Υ	1060.03	
Z	437.60	
RMS	0.07	
Measurements	15	

Circle Relationship A::Cerchio2 dx		
Criteria	Measured	
Diameter	839.01	
Circularity	0.19	
X	1.85	
Y	1060.08	
Z	1107.56	
RMS	0.06	
Measurements	15	

Circle Relationship		
A::Cerchio3 dx		
Criteria	Measured	
Diameter	839.61	
Circularity	0.17	
X	1.10	
Υ	1060.74	
Z	1777.88	
RMS	0.05	
Measurements	13	

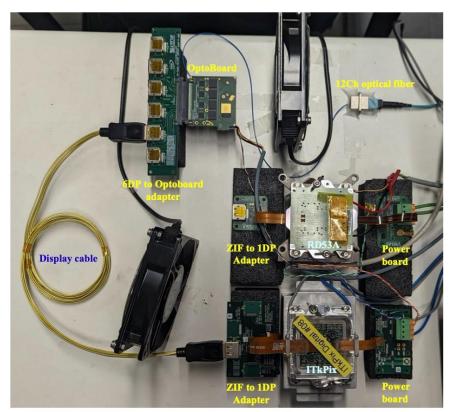
We performed some test for the mating of the cradles but problems raised up. Each part has not bad cylindrical shape but the mating of some part does'nt match, so we decide to simplify the system and check the alignment of the cradles once they are built. The rails now are one part instead being 2 parts in order to gurantee a better alignment.

MAILAS 2 IIK

System Test

Single and multi-module setup

- High Speed data adapter board designed and produced for Pixel community
- DAQ with optical readout
- Data Transmission test



Z. Chubinidze, M. Gatta, M. Beretta, M. Testa

- Develop interlock logics
 - NTC, cooling, power, environmental sensors
- Develop of scalable DCS system

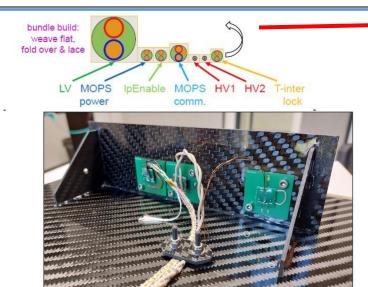


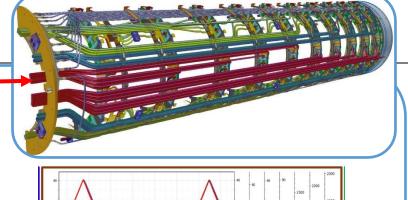
Z. Chubinidze

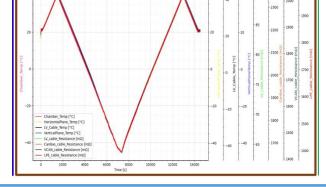


ITk Services

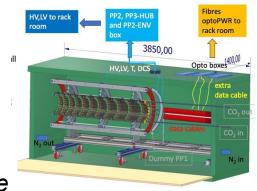
- Power/DCS cables:
- Design, Prototypes and Production
 - Quality Control
 - Thermo-mechanical cycles

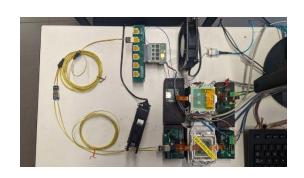


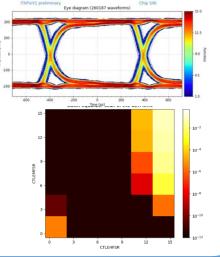




- Extension twinax data cables
 - Design Prototypes and Production
 - Data transmission test







P. Albicocco, M. Testa, Z. Chubinidze



Attività e assegnazioni CIF II Semestre 2025

Attività nel II semestre 2025:

- Finalizzazione dei disegni delle parti mancanti
- Finalizzazione del sistema di sollevamento
- Produzione di alcune parti del tool di assemblaggio
- Montaggio del tool di assemblaggio e test
- Progettazione del sistema di Trasporto

Servizio	Reparto	Assegnato (m.u.)
SEM	Progettazione	4,5
SEM	Costruzioni Meccaniche	10
Supporto Esperimenti	Support Unit	3
SPCM	Progettazione	0,5
SPCM	Meccanica	2



Richieste 2026

ATLAS FTE Totali: 11.25 (Fisici + Tecnologi)

		Richieste (kEUR)
apparati	ATLAS Tier-2	212
consumo	ATLAS	21
missioni	ATLAS	162
consumo	Phase II - ITk	34.5
apparati	Phase II - ITk core	563

Servizi	Richieste <u>stimate</u> 2026 (person months)
Electronics and Automation Service (DR)	12
Mechanics Service (DR)	8 months x 4 persons
Detector Development and Experimental Activities Support Service (DR)	10 months x 2 persons
Servizio Progettazione e Costruzioni Meccaniche (DT)	4
Cryogenic System (DA)	3
Vacuum (DA)	5

